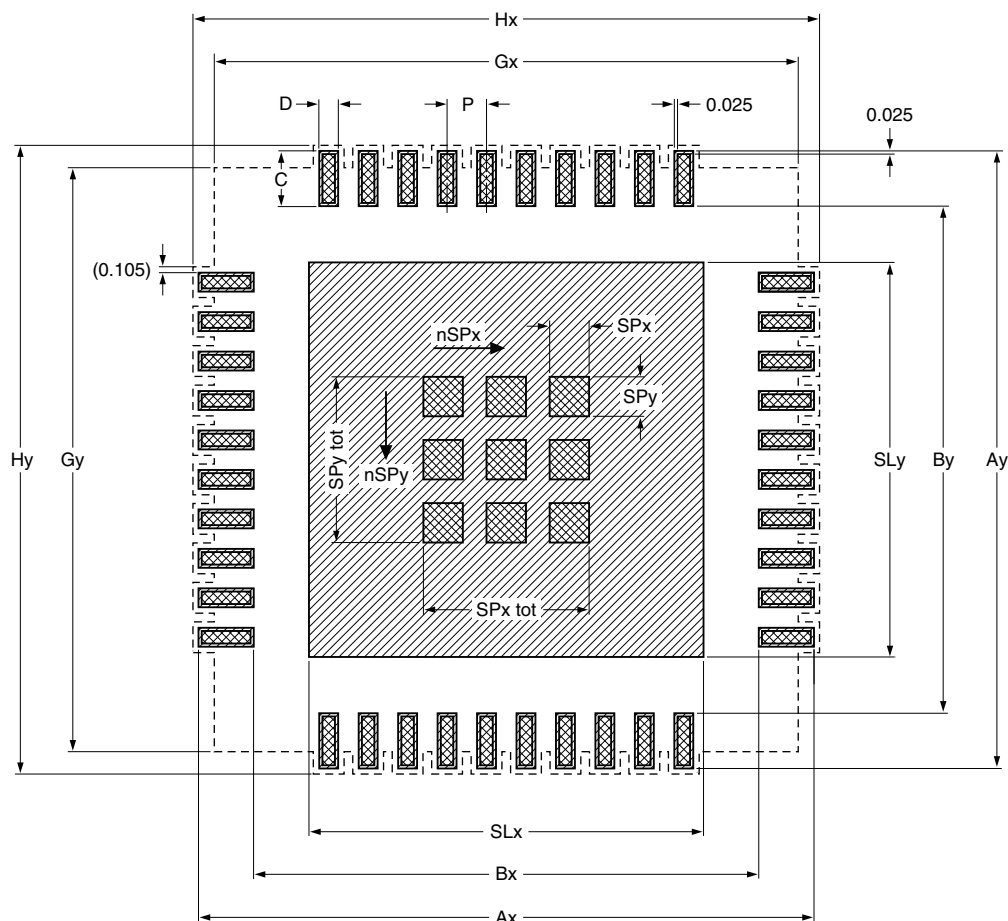





Footprint information for reflow soldering of HVQFN32 package

SOT865-3



Generic footprint pattern

Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

nSPx	nSPy
3	3

Dimensions in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.650	8.000	8.000	5.800	5.800	1.100	0.280	4.700	4.700	2.700	2.700	0.700	0.700	7.300	7.300	8.250	8.250

Issue date ~~09-01-21~~
09-06-15

sot865-3_fr